

Fully automated SMD assembly service with substantially increased capacity provides flexibility, speed and accuracy, resulting in high quality low cost production capability. SMD production line gives assembly possibilities for both RoHS and containing lead projects, where the last one is widely used in medical and military applications.



High precision printer Fuji GPX

PCB size:

Min. 50 mm (L) x 50 mm (W),
Max. 458 mm (L) x 356 mm (W)

PCB load time: 7.5 s

Stability:

high precision printing has been attained for parts from 0402 small chip parts to fine pitch SMD components

Mounting Center i-Pulse M4e

PCB size:

50 mm (L) x 50 mm (W) up to
460 mm (L) x 410 mm (W)

Board thickness: 0.5 up to 2.0 mm

Max. CHIP placement speed:

0.22 s/CHIP

Maks. TSOP placement speed:

0.56 s/TSOP32

Maks. QFP placement speed:

0.82 s/QFP100

CHIP placement accuracy:

+0,06 mm

QFP placement accuracy:

+0,035 mm

Component height: 15 mm

Components applicable:

from 0402 (optimal),
0201 possible also.

Reflow Soldering System SMT XS

Process area length: 2966 mm

Heating modules (pre-heating zones): 3pc.

Heating modules (peak zone):

1 peak zone with 2 heating modules
(1 top and 1 bottom)

Heated tunnel length (total): 2024 mm

Length of active convection zone:

1596 mm

Length of cooling zone: 943 mm

Total air circulation: 8000 m³/tund

Process temperature:

max. 300 °C (pre-heating),
max. 350 °C (peak)

Conveyor width:

60 ... 460 mm (with PCB support)

Conveyor pass through height (top/bottom):

30/30 mm

Conveyor speed: 0.2 ... 3.0 m/min

